

SURFACEMOUNTRECTIFIERS
S8AC--S8MC
FEATURES

- Low profile package
- For surface mounted applications
- High current capability
- Built-in strain relief, ideal for automated placement
- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- High temperature soldering: 250°C/10 seconds at terminals



Lead-free


MECHANICAL DATA

- Case: JEDEC DO-214AB, molded plastic over passivated chip
- Terminals: Solder Plated, solderable per MIL-STD- 750, Method 2026
- Polarity: Color band denotes cathode end

Maximum Ratings(@TA = 25°C unless otherwise specified)

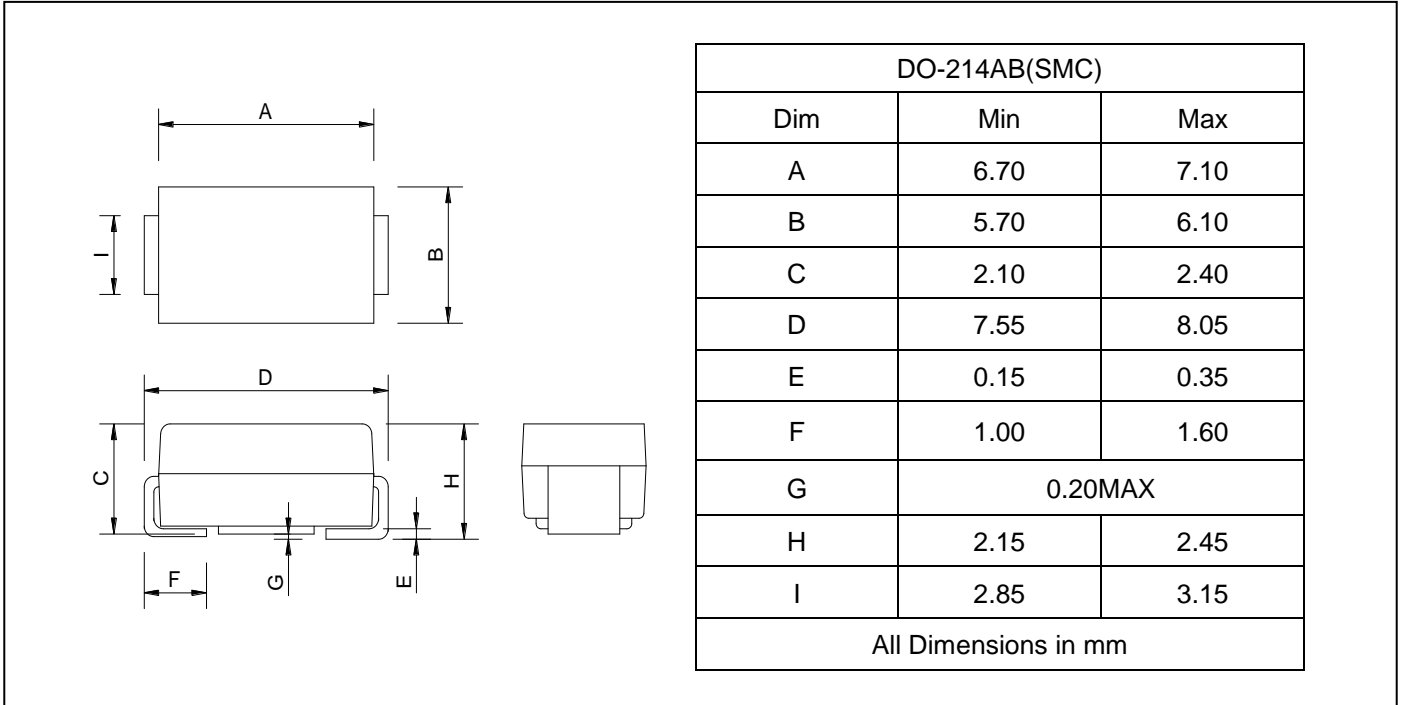
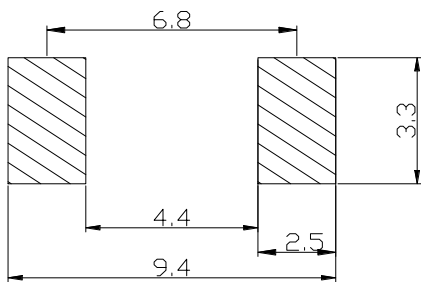
Characteristic	Symbol	S8AC	S8BC	S8DC	S8GC	S8JC	S8KC	S8MC	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RWS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current at $T_L=90^\circ\text{C}$	$I_{F(AV)}$	8.0							A
Peak forward surge current 8.3mssingle half-sine-wave superimposed on rated load(JEDEC Method)	I_{FSM}	200							A

Thermal Characteristics

Characteristic	Symbol	S8AC	S8BC	S8DC	S8GC	S8JC	S8KC	S8MC	UNITS
Operating junction and storage temperature range	$T_J T_{STG}$	-55-----+150							°C

Electrical Characteristics (@TA = 25°C unless otherwise specified)

Characteristic	Symbol	S8AC	S8BC	S8DC	S8GC	S8JC	S8KC	S8MC	UNITS
Maximum Instantaneous Forward Voltage at 8.0A	V_F	1.15							V
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=125^\circ\text{C}$	I_R	10 250							μA

SURFACEMOUNTRECTIFIERS
S8AC--S8MC
PACKAGE OUTLINE DIMENSIONS

SOLDERING FOOTPRINT


Unit : mm

PACKAGE INFORMATION

Device	Package	Shipping
S8AC--S8MC	DO-214AB(SMC)	3000/Tape&Reel